

REMARKS

A Notice of Allowance for the above-captioned application was mailed on March 10, 2005. At this time, the Applicant wishes to amend claims 7, 8 and 9 as shown above in order to more clearly recite the claimed invention. The proposed amendments are:

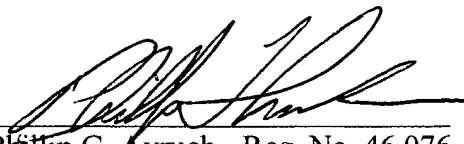
(1) In each of claims 7, 8 and 9, change the term "semiconductor devices," appearing in lines 3 and 4, to --integrated circuits--. The term "integrated circuits" is used in the specification, for example, at page 7, lines 5-10. The amended wording of the claims more clearly distinguishes between the integrated circuits that are formed on the main surface of the semiconductor wafer, and the semiconductor devices that result when the encapsulated semiconductor wafer is divided into individual semiconductor device chips.

(2) In each of claims 7 and 9, line 11, insert the word "wafer" between "semiconductor" and "is." This change is made to assure consistency in terminology in referring to the semiconductor wafer.

It is submitted that the above-described amendments do not change the scope or meaning of the claims, and hence do not affect their allowability. The Applicant believes that the changes to the claims are need for proper protection of the invention and require no substantial amount of additional work on the part of the Office. Accordingly, entry of this Amendment pursuant to 37CFR §1.312, prior to the due date for payment of the issue fee, is respectfully requested.

Respectfully submitted,

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Date


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